

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1406	(board substrate carrier) same (semiconductor chip die) same (land pad) same shap\$3 same hole	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/04 13:15
L2	48	((board substrate carrier) same (semiconductor chip die) same (land pad) same shap\$3 same hole).clm.	US-PGPUB	OR	ON	2005/09/04 13:17
L3	0	((board substrate carrier) same (semiconductor chip die) same (land pad) same shap\$3 same arcuate same hole).clm.	US-PGPUB	OR	ON	2005/09/04 13:17